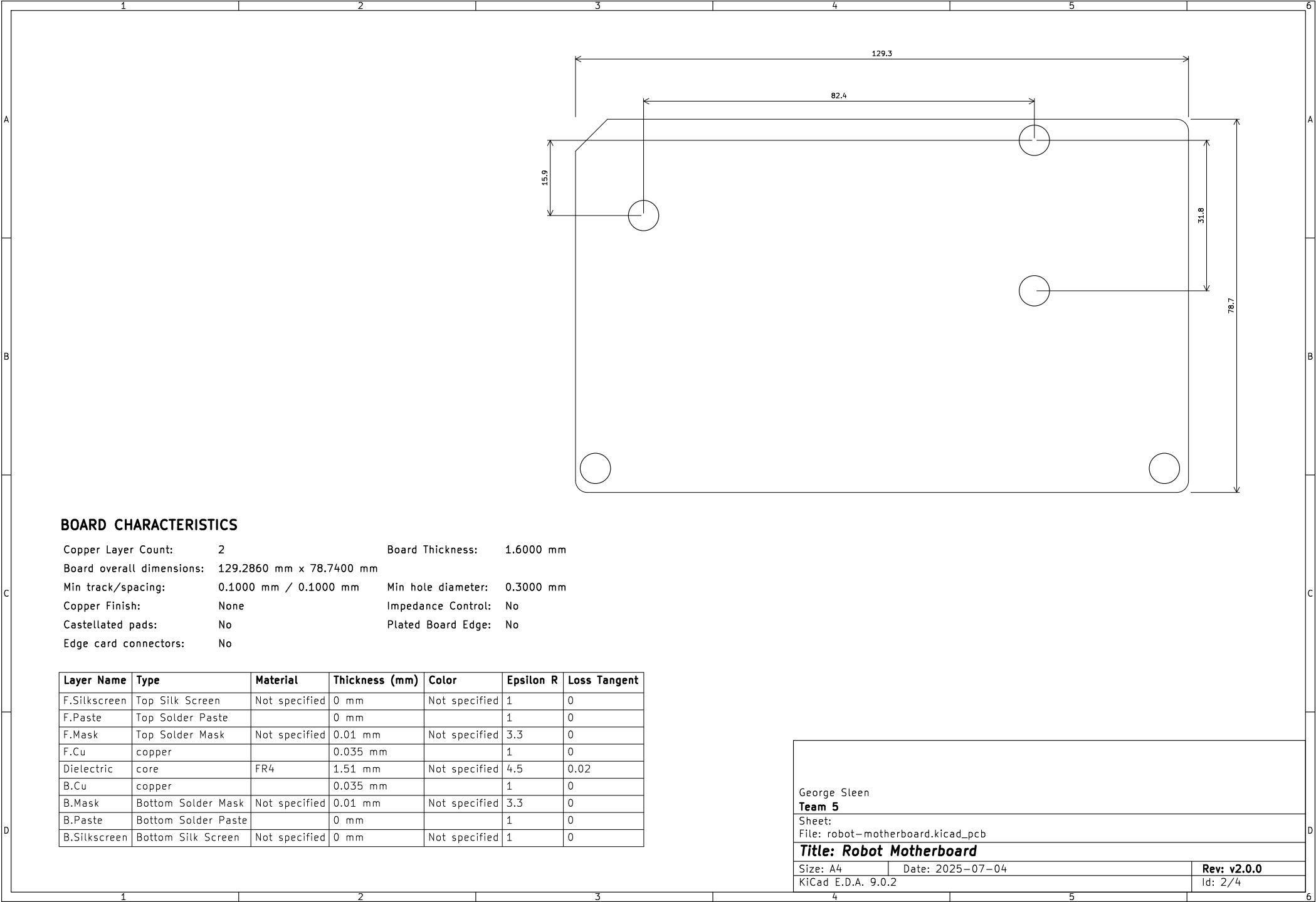


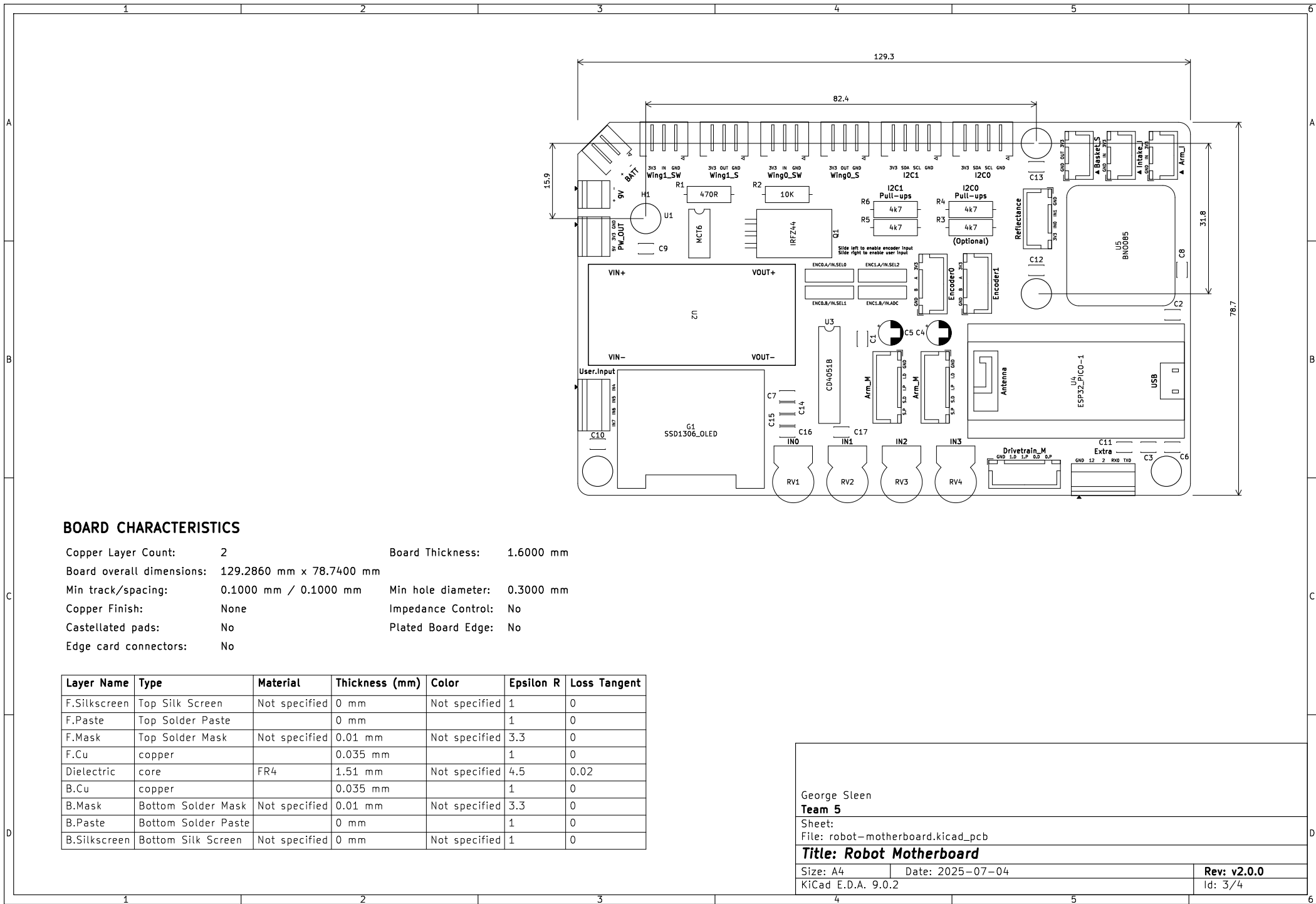
BOARD CHARACTERISTICS

Copper Layer Count: 2 Board Thickness: 1.6000 mm  
Board overall dimensions: 129.2860 mm x 78.7400 mm  
Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.3000 mm  
Copper Finish: None Impedance Control: No  
Castellated pads: No Plated Board Edge: No  
Edge card connectors: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

George Sleen  
Team 5  
Sheet:  
File: robot-motherboard.kicad\_pcb  
Title: Robot Motherboard  
Size: A4 Date: 2025-07-04  
KiCad E.D.A. 9.0.2 Rev: v2.0.0  
Id: 1/4





BOARD CHARACTERISTICS

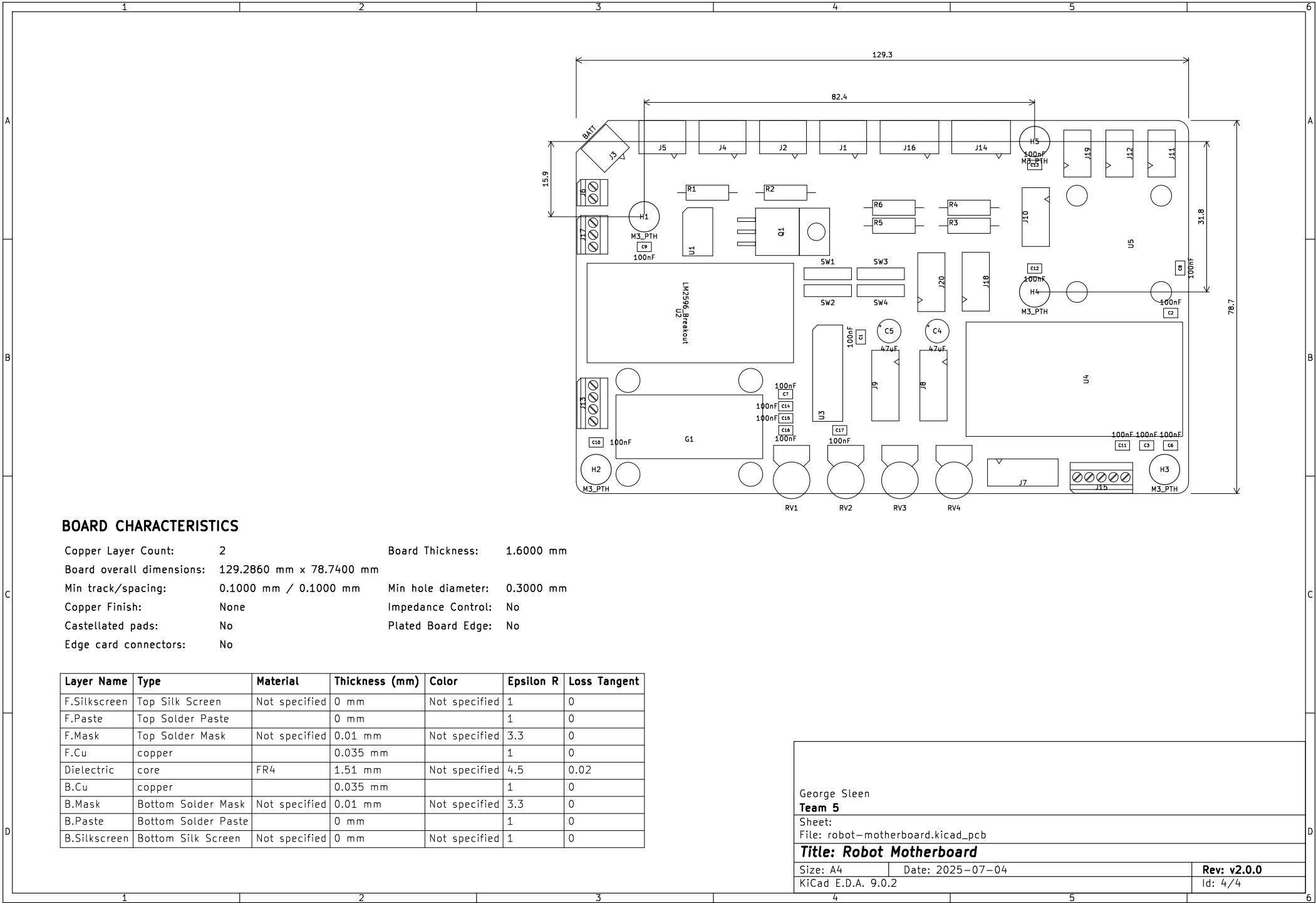
Copper Layer Count:	2	Board Thickness:	1.6000 mm
Board overall dimensions:	129.2860 mm x 78.7400 mm		
Min track/spacing:	0.1000 mm / 0.1000 mm	Min hole diameter:	0.3000 mm
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

George Sleen  
Team 5  
Sheet:  
File: robot-motherboard.kicad\_pcb

Title: Robot Motherboard

Size: A4	Date: 2025-07-04	Rev: v2.0.0
KiCad E.D.A. 9.0.2		Id: 3/4



BOARD CHARACTERISTICS

Copper Layer Count:	2	Board Thickness:	1.6000 mm
Board overall dimensions:	129.2860 mm x 78.7400 mm		
Min track/spacing:	0.1000 mm / 0.1000 mm	Min hole diameter:	0.3000 mm
Copper Finish:	None	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0

George Sleen  
Team 5

Sheet:  
File: robot-motherboard.kicad\_pcb

Title: Robot Motherboard

Size: A4

Date: 2025-07-04

KiCad E.D.A. 9.0.2

Rev: v2.0.0  
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